

Package : WSOF5 / 6 / 6I

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1. Structure and materials

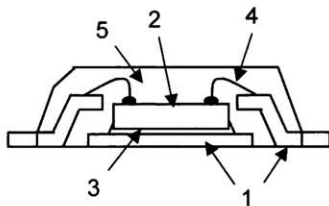


Fig. 1 Structure

No.	Item	Materials
1	Lead Frame	Alloy42 (External lead : Pb free solder plating)
2	Die	Silicon
3	Die Attach	Ag Paste
4	Wire	Au
5	Molding	Epoxy Resin

2. Tape and Reel information

2.1. Packing specification

Tape	Embossed carrier tape (with dry pack)
Quantity	See the table on page 4/4
Direction of feed	TR(See Fig. 2)

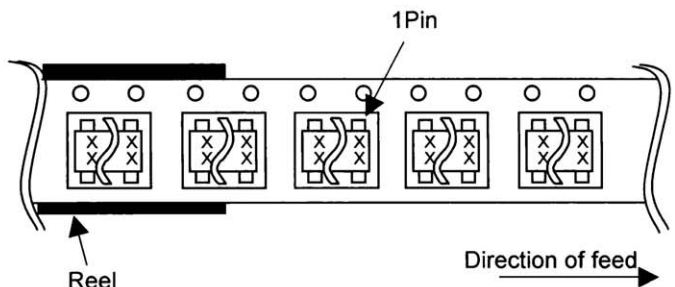


Fig. 2 Typical Tape and Reel configuration

2.2. Tape and Reel specification

2.2.1. Tape and reel dimensions (See the table on page 4/4)

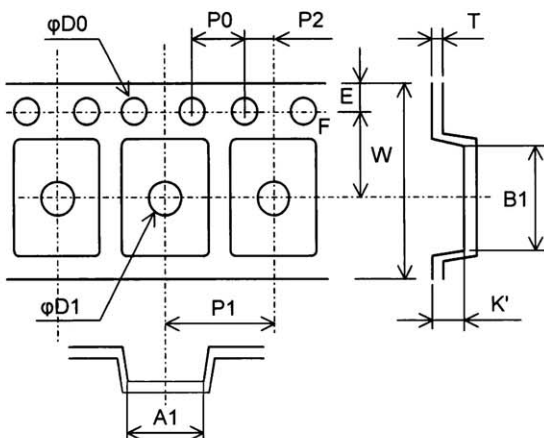


Fig. 3 Tape dimensions

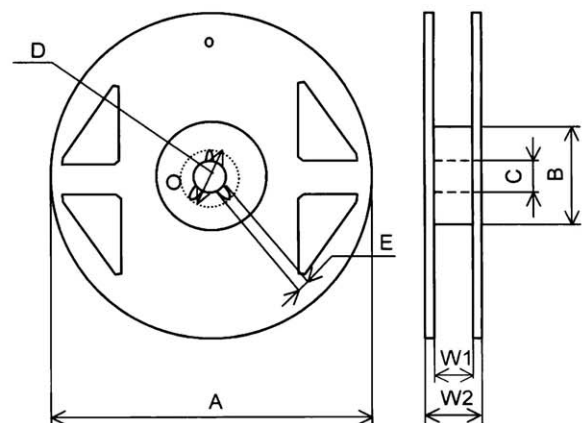


Fig. 4 Reel dimensions

2.3.Leader and Trailer

2.3.1.Leader

No component pockets are 40 pockets or more.

2.3.2.Trailer

No component pockets are 10 pockets or more.

Tape is free from reel.

2.4.Label for Reel and Box

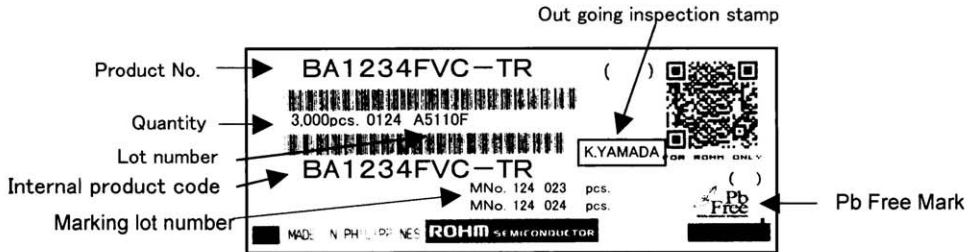


Fig. 5 Label example

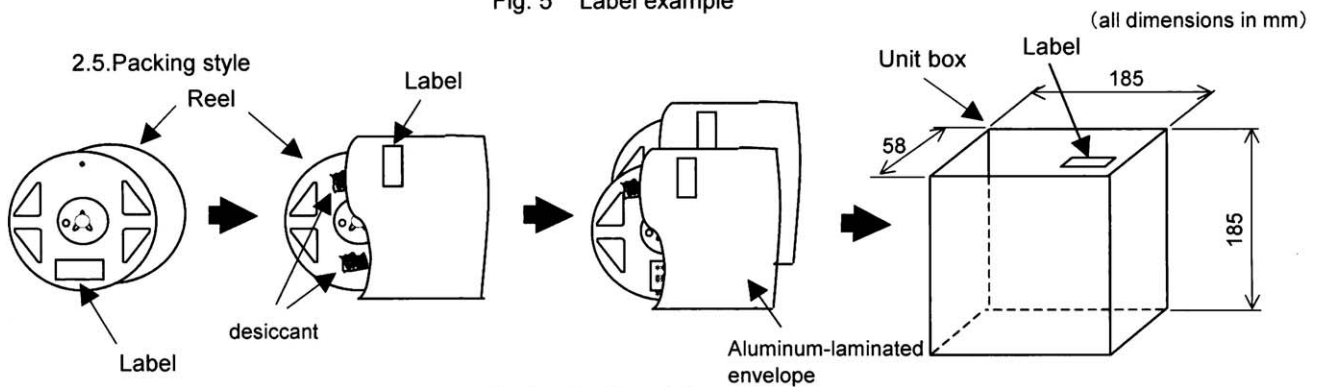


Fig. 6 Packing style

2.6.Shipping style

4unit boxes or less per shipping box

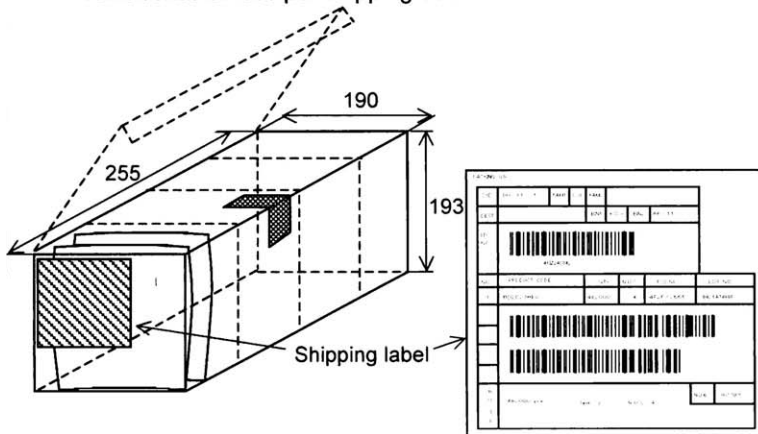


Fig. 7 Shipping box dimensions and Shipping style

2.7.Packing materials

Item	Material
Embossed carrier tape	PS
Cover tape	PET + PE
Reel	PS
Desiccant	Silicagel
Envelope	Aluminum-laminated
Unit box	Cardboard
Shipping box	Cardboard

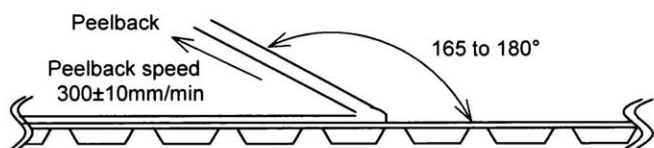
(all dimensions in mm)

2.8.Others

2.8.1.Peelback strength

Cover tape peelback strength is 0.2 to 0.7N.

Fig.8 Test method



2.8.2.Missing lcs

- (1)No consecutive dropouts.
- (2)A maximum 0.1% of specified number of products in each packing may be missing.

3.Storage conditions

3.1.Storage environment

Recommended storage conditions are as follows :

- Temperature : 5 to 30°C
- Humidity : 40 to 70% RH

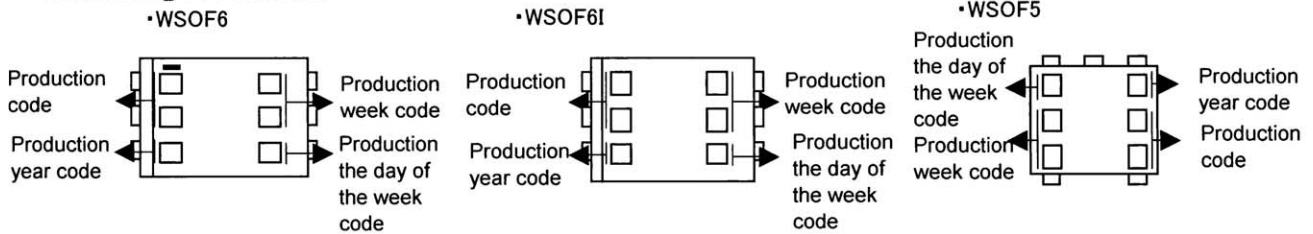
3.2.Storage period

- Specified storage period : 1year

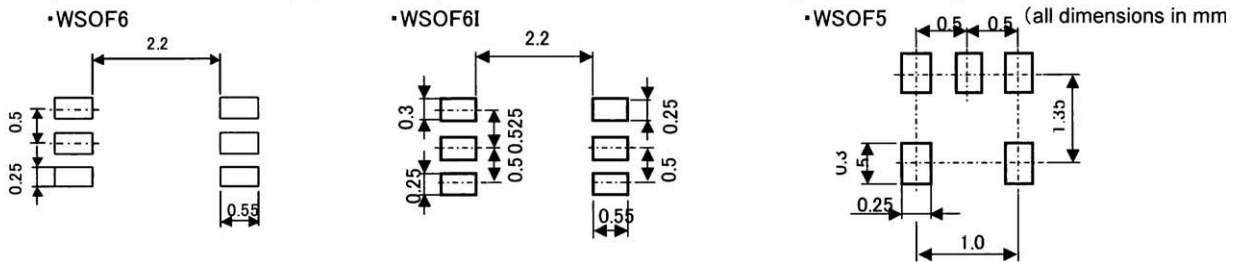
3.3.Specified storage period until soldering

After dry pack is opened , assemble package within 168hours.
 If the storage period has expired , the products must be baked 100°C for 24hours.
 The baking should be max, 2 times due to influence on the product's solderability.
 Execute baking by 60°C/48hours while put in the embossed tape.

4.Marking lot number



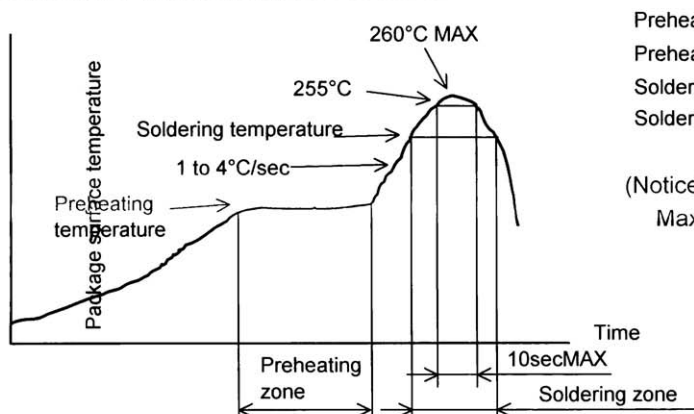
5.Footprint dimensions (Optimize footprint dimensions to the board design and soldering condition)



- *The lead toe and lead side fillet may not be achieved because of non-lead packages.
- *The exposed central pad in the center of the package doesn't require electrical connection to the PCB. The central pad isn't shown in this land pattern, because the quality when connecting it is not guaranteed.

6.Soldering conditions

6.1.Recommended temperature profile for reflow



- Preheating temperature ; 130°C to 190°C
- Preheating zone ; 120sec MAX
- Soldering temperature ; 220°C to 230°C
- Soldering zone ; 60sec MAX

(Notice)
 Maximum 2-times soldering

6.2.The wave soldering method is not supported.

6.3.Recommended condition for solder iron

Recommended condition for solder iron

-Solder iron temperature : 330°C or less

-Mounting time : 3sec or less

(Tape dimensions)

Package	Quantity (pcs)	Tape dimensions (all dimensions in mm)											
		A1	B1	D0	D1	E	F	K'	P1	P2	T	W	P0
WSOF5	3000	1.83	1.83	φ1.5	φ0.5	1.75	3.5	0.75	4.0	2.0	0.25	8.0	4.0
WSOF6	3000	2.0	3.4	φ1.5	φ0.8	1.75	3.5	0.85	4.0	2.0	0.3	8.0	4.0
WSOF6I	3000	2.0	3.4	φ1.5	φ0.8	1.75	3.5	0.85	4.0	2.0	0.3	8.0	4.0
Tolerance		±0.1	±0.1	+0.1/-0	±0.1	±0.1	±0.05	±0.1	±0.1	±0.1	±0.05	±0.3	±0.1

(Reel dimensions)

Package	Reel dimensions (all dimensions in mm)						
	A	B	C	D	E	W1	W2
WSOF5	φ180	φ60	φ13.0	φ20.2	1.5	10.0	16.0
WSOF6	φ180	φ60	φ13.0	φ20.2	1.5	10.0	16.0
WSOF6I	φ180	φ60	φ13.0	φ20.2	1.5	10.0	16.0
Tolerance	MAX	±2.0	±0.5	MIN	MIN	±1.0	MAX

(Dehydrated weight)

Dehydrated weight dimensions in mg
2.8
6.4
6.4

Notes

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